IEEE SW Test Workshop Semiconductor Wafer Test Workshop

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Detecting Killer Particles to Protect Multi-DUT Probe Cards



June 8-11, 2008 San Diego, CA USA Udi Efrat, Guy Kafri, Amir Gilead

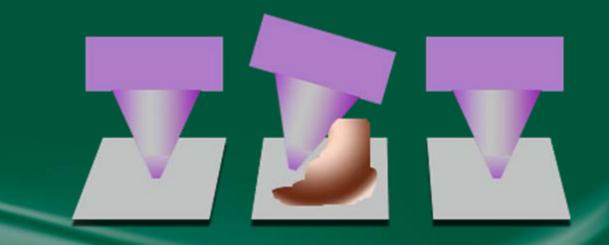
Contents:

- Killer particles!?
- Different probe cards, different particles
- Economies of saving a probe card
- Couldn't regular AOI just scan the wafers?
- Study goal: Telling pebbles from stains
- Study data
- Conclusions



Probe Card Killer Particles

- When a probe tip hits a particle, it may bend permanently
- A bent tip may not create a reliable contact
- Particles come from previous processes
- Certain probe card types are more sensitive than other
- Damage can be costly





Cost of Damaged Card

•	MEMS probe card cost	~\$150÷300K
•	Time to repair at vendor / replace (usually no spare)	2÷3 weeks
•	Cost to repair a damaged tip at vendor	\$1÷5K
•	Tips damaged per occurrence	1÷10
•	Manual inspection detection rate	<60%



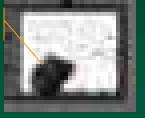
Market Requests

- Numerous customers are buying 2D inspection systems for pre-test inspection to protect probe cards
- Particles on partial and edge die are usually not inspected by conventional 2D AOI, but still present a risk to probe card
- Other customers have requested to perform 3D scan to detect tall defects only
- Complete 3D scan is too slow
- Camtek developed the "Probe Watch™" in response to this need, a relatively fast method covering entire wafer
- This article describes the analysis of the "Probe Watch"



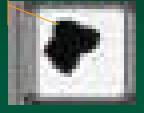
Can't Conventional AOI Just Scan The Wafers?

Area 22x44

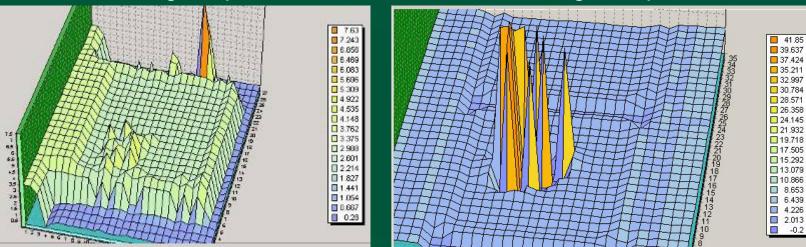


Height 2 µm

Area 35x54



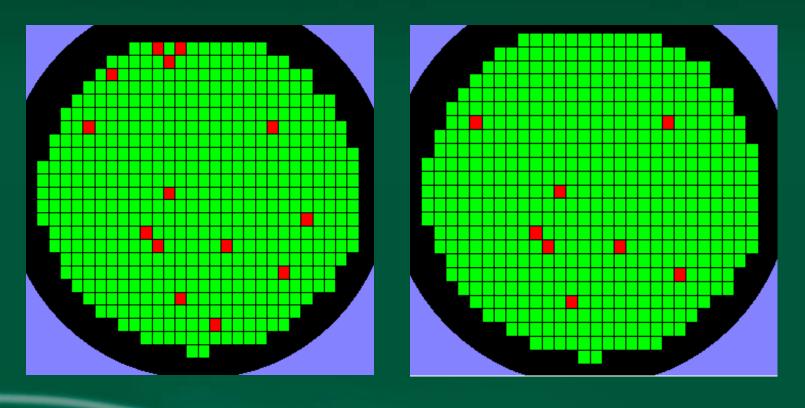
Height 44 µm



Stains and particles look alike in 2D inspection



2D Scan Limitation



2D large defects map (14) Killer defects map (8) Too many false calls!

Goal: Detect Pebbles

- Automatically detect killer particles
- Classify particles by shape and location
- Avoid reporting nuisance particles (stains)
- "Killer Particle" application dependent
- Detect particles on entire wafer area, including perimeter
- Throughput is important



Study Method

- Reference Map
 - Inspect the wafer in 2D, normal magnification
 - Mark blobs larger than 25 µm in any axis
 - Profile each blob with Camtek's Chromatic Confocal Sensor
 - Map blobs taller than 20 µm (=particles)
- Test Map
 - Scan same wafer with new system "Probe Watch™"
 - Map signatures above criterion
- Phase 1: Compare maps
- Phase 2: Correlate Probe Watch signature with particle size*

Size = Particle $(WxLxH)^{0.3}$



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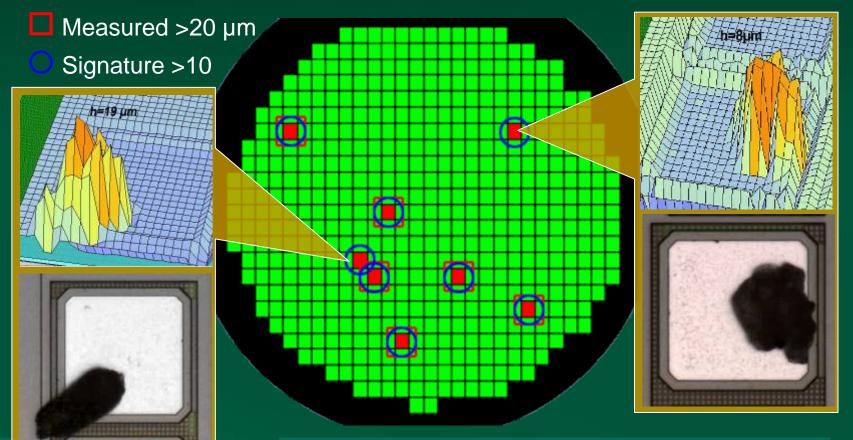
Instrumentation

Falcon 830 equipped with:

- Standard 2D optics and inspection engines
- CCS (Chromatic Confocal Sensor)
- Tested new system = Probe Watch
- High resolution (x20) color review optics
- Wafers with multiple particles of various sizes and shapes to simulate extended production period



Data Sample - Phase 1

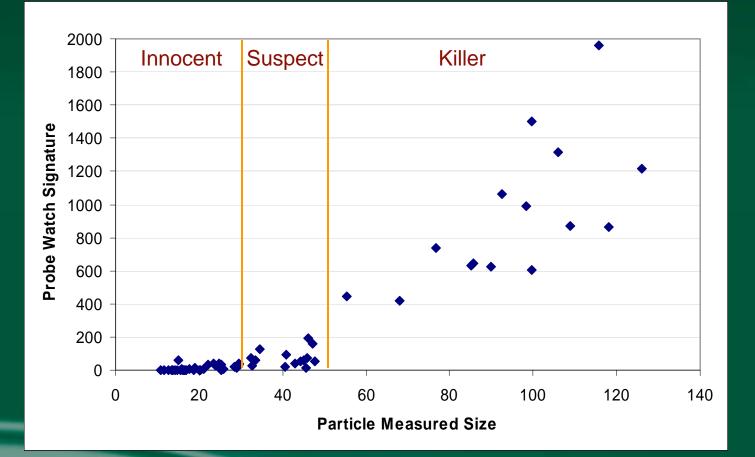


At signature 10, Probe Watch reported:

- All 6 particles marked by CCS
- Plus two particles that may be of interest



Phase 2: Correlation





Probe Watch Test Results

Signature to size* correlation

0.90

Particle Class	Detection Rate	Nuisance Rate
"Killer"	100%	0%
"Innocent"	100%	3%
"Suspect"	71%	0%

Size = Particle $(WxLxH)^{1/3}$



Conclusions

- "Probe Watch" was proven capable of differentiating pebbles from stains and reporting killer defects on entire wafer area
- The system's signature correlated in the study to particle size
- Further characterization needed to adapt the new system to different probe card types and applications, as well as to user preferences
- Camtek will offer the new system as an option on its Falcon line



The more you know

- The cost of collision between a particle and a probe tip can be significant
- Pre-test inspection can now detect killer particles and prevent such collision

Thank You for Your Attention www.camtekusa.com

